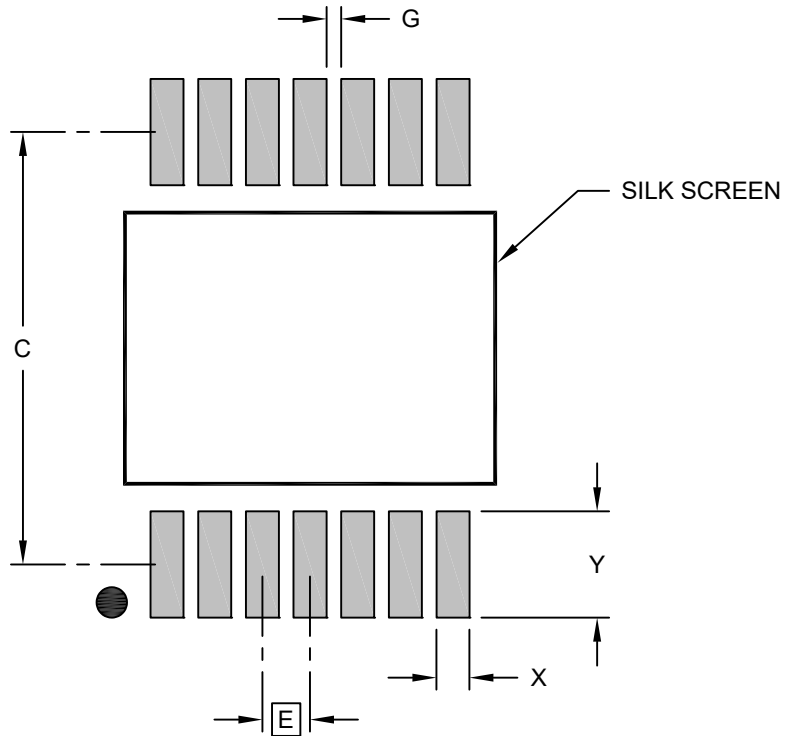


# 14-Lead Thin Shrink Small Outline Package [ST] – 4.4 mm Body [TSSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



## RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Contact Pitch	E		0.65 BSC		
Contact Pad Spacing	C			5.90	
Contact Pad Width (Xnn)	X				0.45
Contact Pad Length (Xnn)	Y				1.45
Contact Pad to Contact Pad (Xnn)	G	0.20			

### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.